

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
RMS Reverse Voltage	V_{RMS}	140	V
DC Blocking Voltage	V_{DC}	200	V
Average Forward Current	I_F	2.6	A
Non Repetitive Peak Surge Current	I_{FSM}	100	A
Thermal Resistance Junction to Case	$R_{\theta JC}$	2.8	/W
Operating and Storage Temperature Range	T_j T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

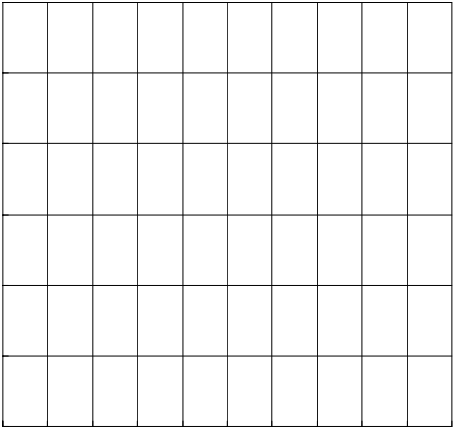
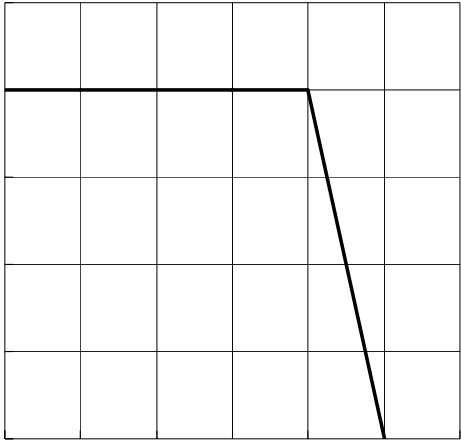
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=2A$ $T_c=25$		0.82		V
		$I_F=2A$ $T_c=125$		0.68		V
		$I_F=6A$ $T_c=25$		0.92	1.0	V
		$I_F=6A$ $T_c=125$		0.82	0.9	V
Instantaneous Reverse Current	I_R Note 1	$V_R=200V$ $T_a=25$			10	μA
		$V_R=200V$ $T_a=125$			150	μA
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{RR}=0.25A$			35	ns

/Notes

4. 采用脉冲测试方法，以减少自热效应。 / Short duration pulse test used to minimize self-heating effect.

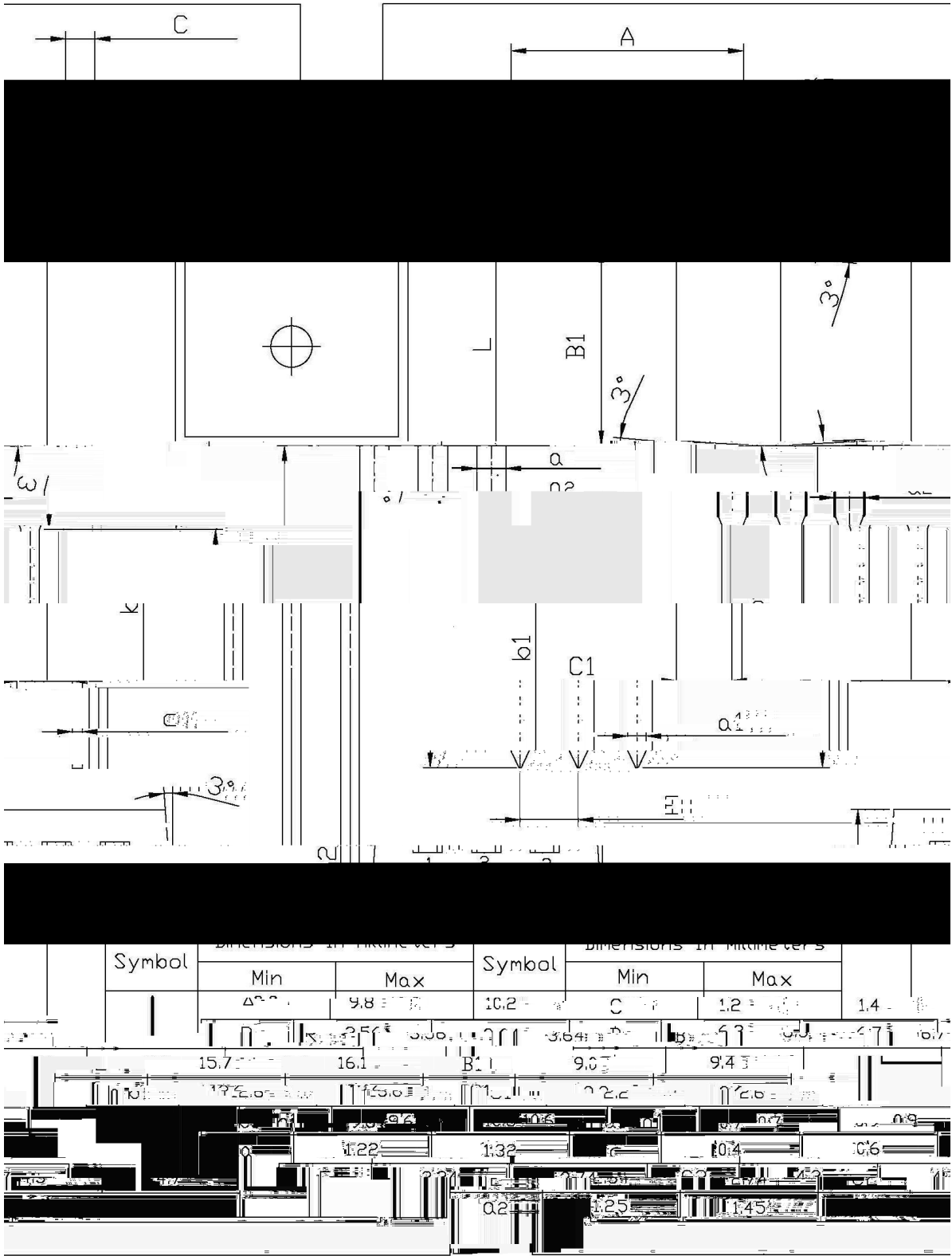
2. 除非另有说明，否则所有参数均为单片值。 / Unless otherwise noted, values for the parameters of a single chip

/ Electrical Characteristic Curve

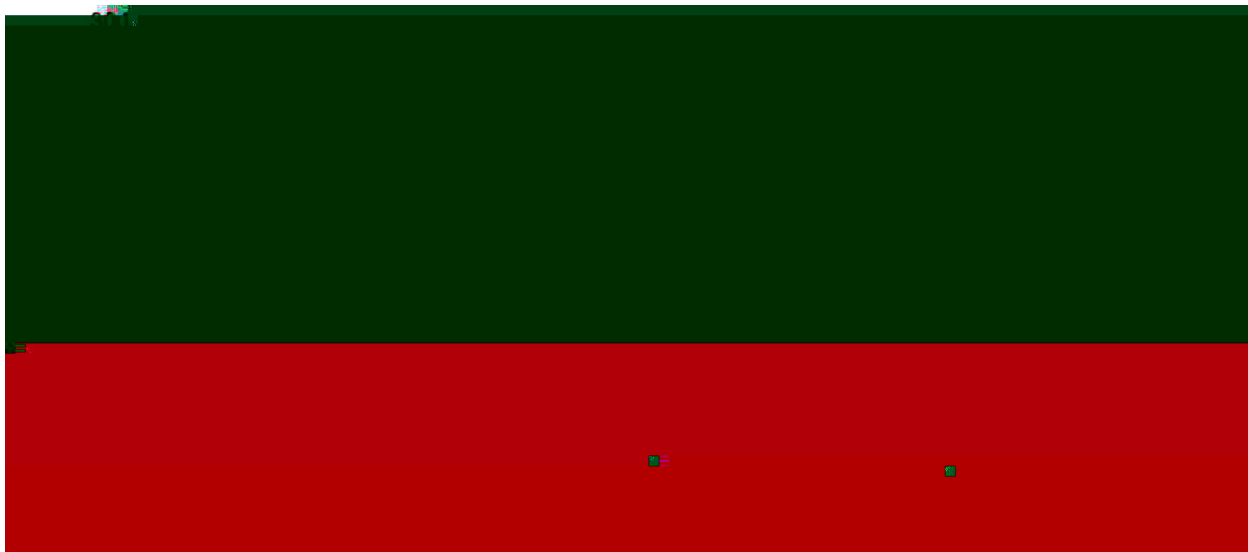


/ Package Dimensions

单位: mm TO-220



() / Temperature Profile for Dip Soldering(Pb-Free)



说明

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255℃, 持续时间: 5~0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

- 1.Preheating:25~150℃, Time:60~90sec.
- 2.Peak Temp.:255℃, Duration:5~0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

测试条件: 270±5℃, 时间: 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

散装 / BULK

Package Type	Units					Dimension (unit mm ³)		

管装 / TUBE

Package Type	Units					Dimension (unit mm ³)		

/ Notices